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The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

Cypress Semiconductor Package Qualification Report

**QTP# 063202 VERSION*A
January 2015**

**≤44-Lead TSOP II
NiPdAu, MSL3, 260C Reflow
CML-R**

**FOR ANY QUESTIONS ON THIS REPORT, PLEASE CONTACT
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PACKAGE QUALIFICATION HISTORY

QUAL REPORT	DESCRIPTION OF QUALIFICATION PURPOSE	DATE COMP.
060905	≤44-Lead TSOP II (without down bonds), using Hitachi-CEL9200CYR Mold Compound, NiPdAu, MSL3, 260C Reflow assembled at CML-R	May 06
063202	≤44-Lead TSOP II NiPdAu, using Kyocera KE-G3000DA (for non-SRAMs), KE-G6000DA (for SRAMs) Mold Compound, MSL3, 260C Reflow assembled at CML-R	Oct 06

MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION	
Package Designation:	ZW44
Package Outline, Type, or Name:	44-Lead Thin Small Outline. Type II
Mold Compound Name/Manufacturer:	Kyocera - KE G3000DA with PMC (for non-SRAMs) Kyocera - KE G6000DA (for SRAMs)
Mold Compound Flammability Rating:	UL94 – V0
Oxygen Rating Index:	None
Leadframe Material:	Copper
Lead Finish, Composition / Thickness:	NiPdAu
Die Backside Preparation Method/Metallization:	Backgrind
Die Separation Method:	100% Saw Through
Die Attach Supplier:	Dexter
Die Attach Material:	QMI509
Die Attach Method:	Epoxy
Bond Diagram Designation	Not Applicable
Wire Bond Method:	Thermosonic
Wire Material/Size:	Au. 1.0 mil
Thermal Resistance Theta JA □C/W:	50.66 °C/W
Package Cross Section Yes/No:	N/A
Assembly Process Flow:	Not Applicable
Name/Location of Assembly (prime) facility:	CML-R
MSL Level	3
Reflow Profile	260C

ELECTRICAL TEST / FINISH DESCRIPTION	
Test Location:	CML-R

RELIABILITY TESTS PERFORMED PER SPECIFICATION REQUIREMENTS

Stress/Test	Test Condition (Temp/Bias)	Result P/F
Temperature Cycle	MIL-STD-883C, Method 1010, Condition C, -65 C to 150 C Precondition: JESD22 Moisture Sensitivity MSL3 192 Hrs 30°C/60%RH+3IR-Reflow, 260°C+0, -5°C	P
Pressure Cooker Test	121°C, 100%RH, 15 Psig Precondition: JESD22 Moisture Sensitivity MSL3 192 Hrs 30°C/60%RH+3IR-Reflow, 260°C+0, -5°C	P
High Accelerated Saturation Test (HAST)	130°C, 3.63V, 85%RH Precondition: JESD22 Moisture Sensitivity MSL3 192 Hrs 30°C/60%RH+3IR-Reflow, 260°C+0, -5°C	P
Acoustics Microscopy	J-STD-020 Precondition: JESD22 Moisture Sensitivity Level (192 Hrs., 30C, 60% RH)	P
Dye Penetration	Test to determine the existence and extent of cracks, Criteria: No Package Crack	P
High Temperature Storage	150°C, no bias	P
X-Ray	MIL-STD-883-2012	P



Reliability Test Data

QTP #: 060905

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
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STRESS: ACOUSTIC, MSL3

CY7C1041BV33 (7C1341C)	4436950	610511269	CML-R	COMP	15	0	
CY7C1041BV33 (7C1341C)	4436950	610511569	CML-R	COMP	15	0	
CY7C1041BV33 (7C1341C)	4435627	610514432	CML-R	COMP	15	0	

STRESS: HI-ACCEL SATURATION TEST, 130C, 3.63V, 85%RH, PRE COND 192HR 30C/60%RH, MSL3

CY7C1041BV33 (7C1341C)	4428378	610510764	CML-R	128	45	0	
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STRESS: HIGH TEMPERATURE STORAGE, no bias

CY7C1041CV33 (7C1341R)	4428378	610514205	CML-R	500	50	0	
CY7C1041CV33 (7C1341R)	4428378	610514205	CML-R	1000	50	0	

STRESS: PRESSURE COOKER TEST, 121C, 100%RH, 15 Psig, PRE COND 192HR 30C/60%RH, MSL3

CY7C1041BV33 (7C1341C)	4428378	610458652	CML-R	168	50	0	
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STRESS: TC COND. C -65C TO 150C, PRE COND 192HR 30C/60%RH, MSL3

CY7C1041BV33 (7C1341C)	4436950	610511269	CML-R	300	50	0	
CY7C1041BV33 (7C1341C)	4436950	610511269	CML-R	500	50	0	
CY7C1041BV33 (7C1341C)	4436950	610511569	CML-R	300	50	0	
CY7C1041BV33 (7C1341C)	4435627	610514432	CML-R	300	50	0	



Reliability Test Data

QTP #: 063202

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS: ACOUSTIC, MSL3							
CY7C1041D (7C1541SC)	4620290	610643650M	CML-R	COMP	15	0	
CY7C1041D (7C1541SC)	4620290	610643650M1	CML-R	COMP	15	0	
CY7C1041D (7C1541SC)	4620290	610643650M2	CML-R	COMP	15	0	
STRESS: DYE PENETRATION							
CY7C1041D (7C1541SC)	4620290	610643650M2	CML-R	COMP	15	0	
STRESS: HIGH TEMPERATURE STORAGE, no bias							
CY62256LL (7A62256E)	4512383	610535998	CML-R	1000	50	0	
STRESS: PRESSURE COOKER TEST, 121C, 100%RH, 15 Psig, PRE COND 192HR 30C/60%RH, MSL3							
CY7C1041D (7C1541SC)	4620290	610643650M	CML-R	168	50	0	
STRESS: TC COND. C -65C TO 150C, PRE COND 192HR 30C/60%RH, MSL3							
CY7C1041D (7C1541SC)	4620290	610643650M	CML-R	300	50	0	
CY7C1041D (7C1541SC)	4620290	610643650M	CML-R	500	50	0	
CY7C1041D (7C1541SC)	4620290	610643650M1	CML-R	300	50	0	
CY7C1041D (7C1541SC)	4620290	610643650M1	CML-R	500	48	0	
CY7C1041D (7C1541SC)	4620290	610643650M2	CML-R	300	50	0	
CY7C1041D (7C1541SC)	4620290	610643650M2	CML-R	500	50	0	
STRESS: X-RAY							
CY7C1041D (7C1541SC)	4620290	610643650M	CML-R	COMP	15	0	



Document History Page

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Rev.	ECN No.	Orig. of Change	Description of Change
**	3840171	HLR	Initial Spec Release.
*A	4629950	HSTO	Align qualification report based on the new template in the front page

Distribution: WEB

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